

Title (en)

SEMICONDUCTOR WAFER CLEANING APPARATUS AND METHOD

Title (de)

VORRICHTUNG UND VERFAHREN ZUR REINIGUNG VON HALBLEITERWAFERN

Title (fr)

APPAREIL ET PROCEDE DE NETTOYAGE DE PLAQUETTE EN SEMI-CONDUCTEUR

Publication

EP 1088337 A1 20010404 (EN)

Application

EP 00918167 A 20000320

Priority

- US 0007394 W 20000320
- US 28161999 A 19990330

Abstract (en)

[origin: WO0059006A1] A cleaning apparatus for removing contaminants from the surface of a semiconductor wafer. A megasonic nozzle and a scrubbing brush are included in the cleaning apparatus. The megasonic nozzle is adapted for outputting megasonically agitated fluid to dislodge contaminant particles from a surface of a semiconductor wafer. The scrubbing brush is adapted to contact the surface of the semiconductor wafer and frictionally remove therefrom the contaminant particles. The megasonic nozzle and the scrubbing brush are both mounted within a cleaning assembly. The cleaning assembly simultaneously employs both the megasonic nozzle and brush to efficiently clean the contaminant particles from the surface of the semiconductor wafer.

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H01L 21/00

IPC 8 full level

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CPC (source: EP KR)

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